# JFETs Switching N-Channel – Depletion



2 SOURCE



**ON Semiconductors Preferred Devices** 

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DS</sub>	30	Vdc
Drain–Gate Voltage	V <sub>DG</sub>	30	Vdc
Gate-Source Voltage	V <sub>GS</sub>	30	Vdc
Forward Gate Current	lG(f)	50	mAdc
Total Device Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	PD	350 2.8	mW mW/°C
Operating and Storage Channel Temperature Range	T <sub>channel</sub> , T <sub>stg</sub>	-65 to +150	°C



#### **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS		· · ·				
Gate–Source Breakdown Voltage $(I_G = 1.0 \ \mu Adc, V_{DS} = 0)$		V <sub>(BR)</sub> GSS	30	_	_	Vdc
Gate Reverse Current $(V_{GS} = 15 \text{ Vdc}, V_{DS} = 0)$ $(V_{GS} = 15 \text{ Vdc}, V_{DS} = 0, T_A = 100^{\circ}\text{C})$		IGSS			1.0 0.2	nAdc μAdc
Drain–Cutoff Current (V <sub>DS</sub> = 15 Vdc, V <sub>GS</sub> = 12 Vdc) (V <sub>DS</sub> = 15 Vdc, V <sub>GS</sub> = 12 Vdc, T <sub>A</sub> = 100°C)		ID(off)	-		1.0 0.1	nAdc μAdc
Gate Source Voltage (V <sub>DS</sub> = 15 Vdc, I <sub>D</sub> = 10 nAdc)	MPF4392 MPF4393	V <sub>GS</sub>	-2.0 -0.5		-5.0 -3.0	Vdc
ON CHARACTERISTICS						
Zero–Gate–Voltage Drain Current(1) (V <sub>DS</sub> = 15 Vdc, V <sub>GS</sub> = 0)	MPF4392 MPF4393	IDSS	25 5.0		75 30	mAdc
Drain–Source On–Voltage $(I_D = 6.0 \text{ mAdc}, V_{GS} = 0)$ $(I_D = 3.0 \text{ mAdc}, V_{GS} = 0)$	MPF4392 MPF4393	VDS(on)	-		0.4 0.4	Vdc
Static Drain–Source On Resistance (I <sub>D</sub> = 1.0 mAdc, V <sub>GS</sub> = 0)	MPF4392 MPF4393	<sup>r</sup> DS(on)	-		60 100	Ω
SMALL-SIGNAL CHARACTERISTICS						
Forward Transfer Admittance $(V_{DS} = 15 \text{ Vdc}, I_D = 25 \text{ mAdc}, f = 1.0 \text{ kHz})$ $(V_{DS} = 15 \text{ Vdc}, I_D = 5.0 \text{ mAdc}, f = 1.0 \text{ kHz})$	MPF4392 MPF4393	У <sub>fs</sub>	-	17 12		mmhos

1. Pulse Test: Pulse Width  $\leq$  300 µs, Duty Cycle  $\leq$  3.0%.

Preferred devices are ON Semiconductor recommended choices for future use and best overall value.

## MPF4392 MPF4393

## **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = $25^{\circ}$ C unless otherwise noted) (Continued)

Characteristic		Symbol	Min	Тур	Max	Unit
SMALL-SIGNAL CHARACTERISTICS (continued)						
Drain–Source "ON" Resistance (VGS = 0, $I_D$ = 0, f = 1.0 kHz)	MPF4392 MPF4393	<sup>r</sup> ds(on)			60 100	Ω
Input Capacitance (V <sub>GS</sub> = 15 Vdc, V <sub>DS</sub> = 0, f = 1.0 MHz)		C <sub>iss</sub>	-	6.0	10	pF
Reverse Transfer Capacitance ( $V_{GS}$ = 12 Vdc, $V_{DS}$ = 0, f = 1.0 MHz) ( $V_{DS}$ = 15 Vdc, I <sub>D</sub> = 10 mAdc, f = 1.0 MHz)		C <sub>rss</sub>	-	2.5 3.2	3.5 -	pF
SWITCHING CHARACTERISTICS						
Rise Time (See Figure 2) $(I_{D(on)} = 6.0 \text{ mAdc})$ $(I_{D(on)} = 3.0 \text{ mAdc})$	MPF4392 MPF4393	tr		2.0 2.5	5.0 5.0	ns
Fall Time (See Figure 4) (VGS(off) = 7.0 Vdc) (VGS(off) = 5.0 Vdc)	MPF4392 MPF4393	t <sub>f</sub>		15 29	20 35	ns
Turn–On Time (See Figures 1 and 2) $(I_D(on) = 6.0 \text{ mAdc})$ $(I_D(on) = 3.0 \text{ mAdc})$	MPF4392 MPF4393	ton		4.0 6.5	15 15	ns
Turn–Off Time (See Figures 3 and 4) (V <sub>GS</sub> (off) = 7.0 Vdc) (V <sub>GS</sub> (off) = 5.0 Vdc)	MPF4392 MPF4393	toff		20 37	35 55	ns

## MPF4392 MPF4393



#### **TYPICAL SWITCHING CHARACTERISTICS**



Figure 5. Switching Time Test Circuit



Figure 6. Typical Forward Transfer Admittance

#### NOTE 1

The switching characteristics shown above were measured using a test circuit similar to Figure 5. At the beginning of the switching interval, the gate voltage is at Gate Supply Voltage ( $-V_{GG}$ ). The Drain–Source Voltage ( $V_{DS}$ ) is slightly lower than Drain Supply Voltage ( $V_{DD}$ ) due to the voltage divider. Thus Reverse Transfer Capacitance ( $C_{rss}$ ) or Gate–Drain Capacitance ( $C_{gd}$ ) is charged to  $V_{GG} + V_{DS}$ .

During the turn–on interval, Gate–Source Capacitance (Cgs) discharges through the series combination of R<sub>Gen</sub> and R<sub>K</sub>. Cgd must discharge to V<sub>DS(on)</sub> through R<sub>G</sub> and R<sub>K</sub> in series with the parallel combination of effective load impedance (R'<sub>D</sub>) and Drain–Source Resistance (rd<sub>s</sub>). During the turn–off, this charge flow is reversed.

Predicting turn–on time is somewhat difficult as the channel resistance  $r_{ds}$  is a function of the gate–source voltage. While  $C_{gs}$  discharges,  $V_{GS}$  approaches zero and  $r_{ds}$  decreases. Since  $C_{gd}$  discharges through  $r_{ds}$ , turn–on time is non–linear. During turn–off, the situation is reversed with  $r_{ds}$  increasing as  $C_{gd}$  charges.

The above switching curves show two impedance conditions: 1)  $R_K$  is equal to  $R_D'$  which simulates the switching behavior of cascaded stages where the driving source impedance is normally the load impedance of the previous stage, and 2)  $R_K = 0$  (low impedance) the driving source impedance is that of the generator.











#### NOTE 2

The Zero–Gate–Voltage Drain Current (IDSS), is the principle determinant of other J–FET characteristics. Figure 10 shows the relationship of Gate–Source Off Voltage (VGS(off)) and Drain–Source On Resistance (rdS(on)) toIDSS. Most of the devices will be within ±10% of the values shown in Figure 10. This data will be useful in predicting the characteristic variations for a given part number.

For example:

Unknown

rds(on) and VGS range for an MPF4392

The electrical characteristics table indicates that an MPF4392 has an I<sub>DSS</sub> range of 25 to 75 mA. Figure 10 shows  $r_{ds(on)} = 52$  Ohms for I<sub>DSS</sub> = 25 mA and 30 Ohms for I<sub>DSS</sub> = 75 mA. The corresponding V<sub>GS</sub> values are 2.2 volts and 4.8 volts.

### PACKAGE DIMENSIONS

TO-92 (TO-226) CASE 29-11 ISSUE AL





NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED. 4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.175	0.205	4.45	5.20	
В	0.170	0.210	4.32	5.33	
С	0.125	0.165	3.18	4.19	
D	0.016	0.021	0.407	0.533	
G	0.045	0.055	1.15	1.39	
Н	0.095	0.105	2.42	2.66	
J	0.015	0.020	0.39	0.50	
K	0.500		12.70		
L	0.250		6.35		
Ν	0.080	0.105	2.04	2.66	
Р		0.100		2.54	
R	0.115		2.93		
V	0.135		3.43		

# <u>Notes</u>

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